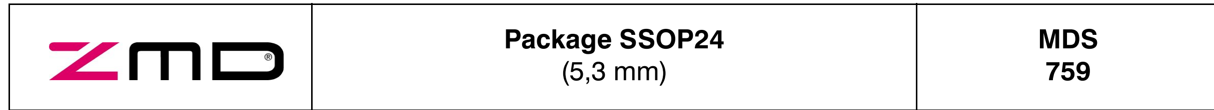


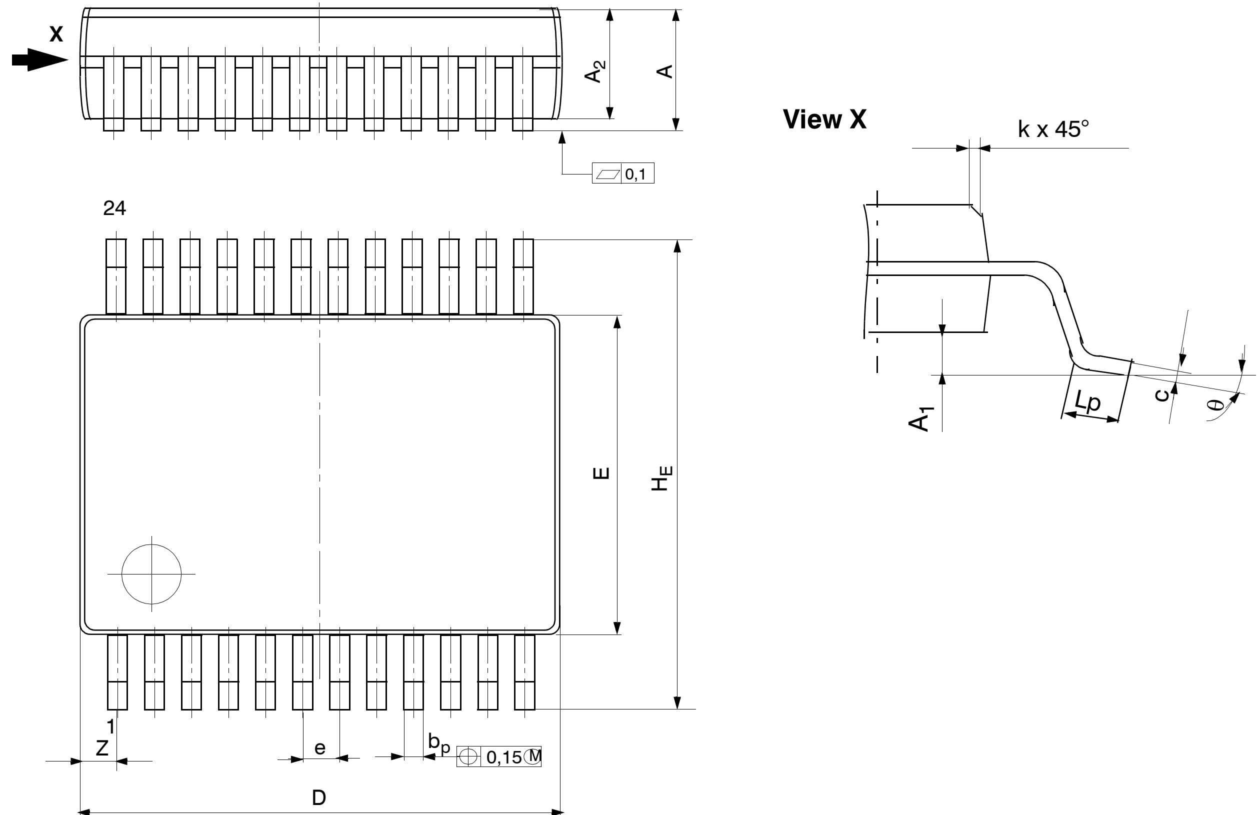
Package SSOP24 (5,3 mm)

MDS 759

Dimensions in millimetres

Based on JEDEC JEP95: MO-150

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	1,99
b_{Pmin}	0,25
b_{Pmax}	0,38
e_{nom}	0,65
H_{Emin}	7,65
H_{Emax}	7,90
L_{Pmin}	0,63
Z_{max}	0,59

Dimensions of Sub-Group C1	
A_{min}	1,73
A_{1min}	0,05
A_{1max}	0,21
A_{2min}	1,68
A_{2max}	1,78
c_{min}	0,09
c_{max}	0,20
D_{min}*	8,07
D_{max}*	8,33
E_{min}*	5,20
E_{max}*	5,38
k_{min}	0,25
θ_{min}	0°
θ_{max}	10°

* without mold-flash

2 Weight ≤ 0,3 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends